

ABSTRACT OF THE DISCLOSURE

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There is provided a semiconductor device and a lead frame that form a stable external ring structure wherein bonding strength and mechanical strength between the external ring and sealing resin is improved. A semiconductor device (1) is formed which comprises a semiconductor chip (2) having a plurality of electrode pads (3) formed at the periphery of a front surface thereof, a wiring film (5) located and formed on the front surface side of the semiconductor chip (2) by laminating an insulation film (7) on a lead pattern (6), outer connection terminals (8) formed so as to protrude above the wiring film (5), a plurality of leads (9) extending from the wiring film (5) and connected to the electrode pads (3) on the semiconductor chip (2) at extended tip ends thereof, an external ring (11) provided so as to surround the semiconductor chip (2) and formed with a plurality of through holes or blind holes (15), and a sealing resin (12) filled between the semiconductor chip (2) and the external ring (11).